ANSYS Named TSMC "Partner of the Year"

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PITTSBURGH, Oct. 6, 2015 /PRNewswire/ -- TSMC has honored ANSYS (NASDAQ: ANSS) with its 2015 Open Innovation Platform[®] (OIP) Partner of the Year award for joint development of the 10nm FinFET design infrastructure to address the power integrity and reliability requirements for chip applications.



The award is given to TSMC OIP partners that have made significant contributions toward the development of design infrastructure for their latest process technologies. ANSYS was recognized for advanced power noise, electromigration (EM) and thermal reliability solutions that helped enable TSMC's 10 nanometer FinFET technology deployment. This technology enables users to innovate the next generation of system on a chip (SoC) designs for use in emerging mobile, computing and networking applications.

"TSMC is an industry visionary – and ANSYS is proud and humbled to partner with this remarkable organization," said John Lee, general manager, ANSYS. "Together we continue to help the semiconductor industry push the boundaries of innovation and to have a positive impact on our lives."

"ANSYS has been a long-term partner to TSMC, collaborating with us to jointly bring deep technical experience to address the new power, EM and thermal reliability challenges associated with next-generation products," said Suk Lee, TSMC senior director, design infrastructure marketing division. "This award is well deserved, and we look forward to extending our collaboration so our customers can continue to produce the most cutting-edge products on the planet."

About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs over 2750 professionals, many of them expert in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit <u>www.ansys.com</u> for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansys.com/Social@ANSYS

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